

COMMON MODE CHOKES FASF1608,2012LP SERIES



FEATURES:

Special very Low profile and very small size SMD Design, Wound chip construction with standard 160808 or 201209 size, with best EMI suppression effect at higher frequency 500MHz~up And least impact to signal wave form.

APPLICATIONS:

Preventive measure against high speed signal radiation emissions such as USB 2.0 IEEE1394 or LAN interface Best for NB, DSC, mobile device design.

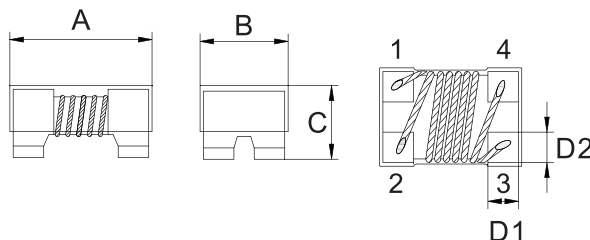
GENERAL SPECIFICATIONS:

Impedance tolerance: Min at 20°C.
Operating temperature: -20°C to +105°C.
Storage Temp: -0°C to +40°C.
Resistance to Soldering Heat: 260°C for 10 sec.
Temperature Rise: 40°C Typ. at Rated Current.
All parts meet ROHS compliance.

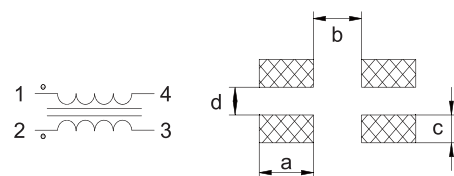
ELECTRICAL CHARACTERISTICS

Part Number	Impedance [Ω] $\pm 25\%$ 100MHz	D.C. Resistor [Ω] Max at 20°C	Rated current (mA) Max	Part Number	Impedance [Ω] $\pm 25\%$ 100MHz	D.C. Resistor [Ω] Max at 20°C	Rated current (mA) Max
FASF1608LP-100	10	0.30	500	FASF2012LP-120	12	0.25	500
FASF1608LP-200	20	0.40	400	FASF2012LP-900	90	0.35	400
FASF1608LP-300	30	0.45	350	FASF2012LP-121	120	0.40	500
FASF1608LP-450	45	0.50	300	FASF2012LP-181	180	0.50	250
FASF1608LP-600	60	0.50	300				
FASF1608LP-670	67	0.50	300				
FASF1608LP-900	90	0.55	250				
FASF1608LP-121	120	0.80	200				
FASF1608LP-161	160	0.80	200				

TECHNICAL INFORMATION



ELECTRICAL SCHEMATIC & PAD LAYOUT



DIMENSIONS:MM

Part number	A	B	C	D1	D2	a	b	c	d
FASF1608LP	1.20 \pm 0.2	1.00 \pm 0.2	0.90 \pm 0.2	0.36 REF	0.38 REF	0.45 REF	0.60 REF	0.45 REF	0.30 REF
FASF2012LP	2.00 \pm 0.2	1.20 \pm 0.2	1.20 \pm 0.2	0.45 REF	0.40 REF	0.90 REF	0.80 REF	0.40 REF	0.40 REF